## Patent Abstracts of Japan

PUBLICATION NUMBER

06204291

**PUBLICATION DATE** 

22-07-94

APPLICATION DATE

28-12-92

**APPLICATION NUMBER** 

04360574

APPLICANT: ROHM CO LTD;

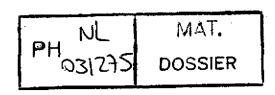
INVENTOR: TSUMORI MASAHIKO;

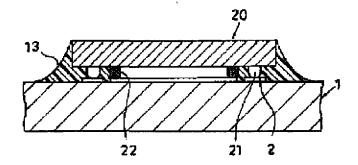
INT.CL.

: H01L 21/60 H01L 21/56 H01L 23/28

TITLE

SEMICONDUCTOR DEVICE





ABSTRACT: PURPOSE: To provide a semiconductor device which protects the electric properties of

the semiconductor device and secures reliability to a satisfactory extent.

CONSTITUTION: A ring-shaped dam 22, which is made of the metallic material same as a

metallic bump 21, is formed inside the metallic bump 21 formed on the surface of a semiconductor element 20, which makes it possible to prevent low viscosity sealing resin

13 from flowing into the main circuit area of the semiconductor element 20.

COPYRIGHT: (C)1994, JPO& Japio